



Material declaration form

General Information			
IPC	1752	Version	2
Form type*	Distribute		
Sectionals*	Material information	Subsectionals*	A-D
	Manufacturing information		*: Required Field

Supplier Information			
Company name*	STMicroelectronics	Response Date*	2024-08-09
Contact name*	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact phone*	Refer to Supplier Comment section	Contact email*	Refer to Supplier Comment section
Authorized representative*	MDG CHAMPION	Representative title	MDGMaterial Declaration champion
Representative phone*	Refer to Supplier Comment section	Representative email*	Refer to Supplier Comment section
Supplier comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty statement

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Legal statement

Supplier acceptance*	true	Legal declaration*	Standard
Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.			



Product				
Mfr item number	Mfr item name	Version	Manufacturing site	date
STM32H725AGI6	20OQ*483XXXZ	A	9991	2024-08-09
	Amount	Unit of measure	Unit type	ST ECOPACK grade
	68	mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL rating	Classification temperature	Number of reflow cycles		
3	260	3		
Bulk solder termination	Terminal plating	Terminal base alloy	Comment	
Tin - 3.5Ag	Not Applicable	NAC	0	
Package designator	Package size	Number of instances	Shape	
BGA	7x7	169	Bulk solder	
Comment	Package : A0YV UFBGA 7X7X0.6 169L P 0.5 MM 8502430			

QueryList : RoHS Directive 2011/65/EU- 8 June 2011 – Annex II amended by Delegated Directive 2015/863 - 31 March 2015		Response
1 - Product(s) meets EU RoHS requirement without any exemptions		true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)		false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)		false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions		false
Exemption Id.	Description	

QueryList : REACH-27th June 2024				Response
QUERY				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
	0			



Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	200Q*483XXXZ		68.0000		6000000.0	1000000.0				
Homogeneous material	Material group	Mass	Unit of measure	Level	Substance category	Substance	CAS	Exempt	Mass	Unit of measure	Concentration in homogeneous material (ppm)	Concentration in product (ppm)				
Die or dies	M-011 Other inorganic materials	2.782	mg	supplier	die	Silicon (Si)	7440-21-3		2.682	mg	964032	39440				
				supplier	metallization	Aluminium (Al)	7429-90-5		0.012	mg	4244	174				
				supplier	metallization	Copper (Cu)	7440-50-8		0.037	mg	13380	547				
				supplier	metallization	Nickel (Ni)	7440-02-0		0.000	mg	72	3				
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.006	mg	2158	88				
				supplier	metallization	Titanium (Ti)	7440-32-6		0.001	mg	360	15				
				supplier	metallization	Tungsten (W)	7440-33-7		0.000	mg	72	3				
				supplier	Passivation	Silicon Oxide	7631-86-9		0.044	mg	15682	642				
				supplier	Substrate	Continuous Filament Fiber Glass	65997-17-3		2.531	mg	130000	37214				
				supplier	Substrate	Bismaleimide	105391-33-1		1.071	mg	55000	15745				
Substrate (A26880)	Copper & its alloys	19.466	mg	supplier	Substrate	Triazine	25722-66-1		1.071	mg	55000	15745				
				supplier	Substrate	Epoxy Resin	9003-36-5		2.141	mg	110000	31489				
				supplier	Substrate	Inorganic filler	24623-77-6		0.973	mg	50000	14313				
				supplier	Substrate	Copper (Cu)	7440-50-8		6.229	mg	320000	91605				
				supplier	Substrate	Gold (Au)	7440-57-5		0.389	mg	20000	5725				
				supplier	Substrate	Nickel(Ni)	7440-02-0		1.363	mg	70000	20039				
				supplier	Substrate	Acrylic Resin	Proprietary		0.973	mg	50000	14313				
				supplier	Substrate	Barium Sulfate	7727-43-7		0.584	mg	30000	8588				
				supplier	Substrate	Silica	7631-86-9		0.389	mg	20000	5725				
				supplier	Substrate	Talc	14807-96-6		0.389	mg	20000	5725				
				supplier	Substrate	Dipropylene Glycol Monomethyl Ether	34590-94-8		0.389	mg	20000	5725				
				supplier	Substrate	3-Methoxy-3-Methyl Butyl-Acetate	Proprietary		0.389	mg	20000	5725				
				supplier	Substrate	Epoxy Resin	85954-11-6		0.584	mg	30000	8588				
				Glue epoxy (ATB-125-12)	Precious metals	3.996	mg	supplier	Glue or tape	Butadiene, acrylonitrile polymer, carboxy-termin	68610-41-3		2.597	mg	650000	38197
								supplier	Glue or tape	Formaldehyde, polymer with (chloromethyl)oxir	37382-79-9		0.999	mg	250000	14691
supplier	Glue or tape	Dapsone	80-08-0						0.240	mg	60000	3526				
supplier	Glue or tape	[3-(2,3-Epoxypropoxy)propyl]trimethoxysilane	2530-83-8						0.080	mg	20000	1175				
supplier	Glue or tape	Reaction product: bisphenol-A-(epichlorhydrin);	25068-38-6						0.080	mg	20000	1175				
Bonding wire (Cu)	Precious metals	1.663	mg	supplier	Bonding wire	Copper (Cu)	7440-50-8		1.606	mg	965500	23612				
				supplier	Bonding wire	Palladium (Pd)	7440-05-3		0.052	mg	31000	758				
				supplier	Bonding wire	Gold (Au)	7440-57-5		0.006	mg	3500	86				
Encapsulation (KE-G1250AAS)	Other inorganic materials	35.983	mg	supplier	Molding Compound	Silica(Fused)	60676-86-0,7631-86-9		32.385	mg	900000	476246				
				supplier	Molding Compound	Epoxy resin	Proprietary		1.907	mg	53000	28046				
				supplier	Molding Compound	Phenol resin	Proprietary		1.547	mg	43000	22754				
				supplier	Molding Compound	Carbon Black	1333-86-4		0.144	mg	4000	2117				
Solder Ball (96.5Sn/3.5Ag)	Other Nonferrous metals & alloys	4.110	mg	supplier	Matte Sn	Tin (Sn)	7440-31-5		3.966	mg	965000	58326				
				supplier	Matte Sn	Silver (Ag)	7440-22-4		0.144	mg	35000	2115				